

Notice of References Cited	Application/Control No. 10/720,839	Applicant(s)/Patent Under Reexamination STEGEER, ROBERT J.	
	Examiner Stanley J. Pruchnic, Jr.	Art Unit 2859	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,549,756 A	08-1996	Sorensen et al.	118/715
	B	US-5,806,980 A	09-1998	Berrian, Donald W.	374/179
	C	US-2003/0029835 A1	02-2003	Yauw et al.	216/67
	D	US-2003/0036877 A1	02-2003	Schietinger, Charles W.	702/134
	E	US-6,647,350 B1	11-2003	Palfenier et al.	702/134
	F	US-6,799,137 B2	09-2004	Schietinger et al.	702/134
	G	US-2004/0208228 A1	10-2004	Hashikura et al.	374/179
	H	US-6,816,803 B1	11-2004	Palfenier et al.	702/134
	I	US-2004/0261721 A1	12-2004	Steger, Robert J.	118/728
	J	US-2005/0037617 A1	02-2005	Magni, Enrico	438/689
	K	US-6,862,549 B1	03-2005	Palfenier et al.	702/134
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Muller, "Control of Reactive Ion Etching Process for InP and Related Materials by In Situ Ellipsometry in the Near Infra Red," 2 nd Intl Cont, Lib. of Cong. #90-80596, IEE Cat. No. 90CH2859-7, pp. 211-214 (April 1990).
	V	Gabriel et al., "In situ wafer temperature measurement during plasma etching," Solid State Technology Magazine, PennWell Corp., Vol. 42, No. 10, October 1999 (6 pages)
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.